## Seminar

## Institute for Plasma Research

| Title:   | Excitation of Terahertz Surface Magnetoplasmons by Laser on |
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|          | Graphene–n-InSb Semiconductor Surface                       |
| Speaker: | Dr. Rohit Kumar Srivastav                                   |
|          | Institute for Plasma Research, Gandhinagar                  |
| Date:    | 06th June 2025 (Friday)                                     |
| Time:    | 10:30 AM  |
| Venue:   | Seminar Hall, IPR   |

## Abstract

A mechanism is proposed for the resonant excitation of terahertz (THz) surface magnetoplasmons (SMPs) via the oblique incidence of a p-polarized laser beam on a graphene sheet deposited over a rippled surface of an n-type InSb semiconductor, under the influence of an external magnetic field. The magnetic field, applied parallel to the semiconductor surface, modifies the SMPs dispersion [1]. The graphene layer, which can be fabricated using chemical vapor deposition (CVD) or plasma-enhanced chemical vapor deposition (PECVD), introduces enhanced surface conductivity ( $\sigma_g$ ), supporting the propagation of strong surface plasmons [2-3]. The resonant excitation of THz SMPs, periodic ripple surface provides the extra momentum for the phase-matching conditions. The incident laser imparts a linear oscillatory velocity to free electrons, which, when coupled with a modulated electron density, generates a linear current density that acts as a source for THz SMPs generation. It is shown that the amplitude of the THz SMP wave can be tuned by adjusting the external magnetic field (B<sub>0</sub>), the graphene's Fermi energy (E<sub>F</sub>), the semiconductor's temperature (T), and the incident angle ( $\theta$ ) of the laser. This mechanism holds promise for the development of actively tunable plasmonic devices. [4-5].

## References:

- [1] J. Brion, et. al., Physical Review. Letters. 28 1455 (1972).
- [2] F. Liu, et. al., Advanced Functional Materials 32, 2203191 (2022).
- [3] M. Saeed, et. al., Molecules 25, 3856 (2020).
- [4] I. F. Akyildiz, et. al., IEEE Transactions on Communications 70, 4250 (2022).
- [5] K. Liu, et. al., Nature Communications 15, 8037 (2024).
- [6] R. K. Srivastav and M. Kundu, Physical Review E (2025), Submitted.